

## Registration.

ADMISSION TO THE FAIR ON ALL FOUR DAYS IS INCLUDED.

Act now and register for the conference so that you can be part of the embedded sector's communication and networking event on Planet e.

If you register by September 30, 2016, you can secure yourself an Early Bird discount.

**Additional information:**  
[electronica.de/en/embeddedplatforms](http://electronica.de/en/embeddedplatforms)

## Travel/Accommodations.

Whether you come by car or public transportation: Planet e is quick and easy to reach.

**Additional information:** [electronica.de/travel](http://electronica.de/travel)

Act now and reserve a hotel room for a relaxed stay.

**Additional information:** [electronica.de/accommodation](http://electronica.de/accommodation)

## SPONSORS



## ORGANIZER/ INFORMATION

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## PLANET E ON WWW

What's new on Planet e, and what is the industry talking about? You can stay up to date at all times here:  
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## CONTACT

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Multiple responses possible in some cases. Last updated: 08/2016



Messe München  
Connecting Global Competence

# Embedded Platforms Conference.

International Conference on Future-Proof  
Hardware and Software Platforms.

**November 9–10, 2016 | Messe München**



## Conference Program

The conference is held within the scope of [electronica 2016](http://electronica.de).  
[electronica.de](http://electronica.de)



**electronica** 2016  
inside tomorrow

## Embedded platforms are the raw material for a digital future.

Future trends such as Industry 4.0, autonomous driving, the smart grid, smart buildings, wearables, 3D printing and virtual reality call for intelligent and networkable embedded platforms. The objective: New kinds of functions and services that work reliably and give rise to new business models.

In this regard, the Embedded Platforms Conference serves as a valuable communication platform for users and solution providers of components and tools. As one of the three pillars on the topic of embedded along with the Embedded Forum and the Embedded exhibition sector, it features an extensive range of information at **e**lectronica. Everything that companies need to develop future-oriented embedded platforms is available here—compact and clearly organized at a single location.

This year, the conference will shed light on modern embedded platforms from the perspective of **microcontrollers, peripherals, security, sensor technology, energy supplies and communication**—and the **Internet of Things** is always in sight. Together with the unique range of information at **e**lectronica, the program of the Embedded Platforms Conference offers you a number of new ideas. Details are available in this flyer. Let yourself be inspired.

Sincerely yours,



A handwritten signature in black ink that reads "Peter Siwon".

Peter Siwon  
MicroConsult GmbH  
Program Committee



A handwritten signature in black ink that reads "J. Wiesböck".

Johann Wiesböck  
Vogel Business Medien GmbH & Co. KG  
Program Committee

## Only on Planet e – Exhibition, forum, conference.

**e**lectronica's **3-pillar concept** gives you a unique opportunity to deepen your understanding of the conference themes directly at the fair, i.e. with hundreds of exhibitors and at the **e**lectronica Embedded Forum.

### CONFERENCE

The communication and networking event in the embedded sector on Planet **e**. Leading suppliers and independent experts give visitors an overview of and insights into the ecosystems of modern embedded platforms.

- ▶ International experts from upper management
- ▶ More than 160 participants from 15 countries in 2014
- ▶ Highlight topics in 2016: IoT and security, microcontrollers and peripherals, power and sensors (incl. wireless charging) and embedded communications

### FORUM

Presentations of technical papers about technologies, trends and product innovations that cover the entire range of embedded technologies.

- ▶ Topics: from chips and components to tools and software, boards and modules for various applications and from the Internet of Things to industrial electronics and automation.
- ▶ Perfect location at the heart of the embedded exhibition sector in Hall A6.

### EXHIBITION

The clearly organized exhibition covers the entire range of state-of-the-art technology.

- ▶ 323 companies at **e**lectronica 2014 presented innovations for the embedded sector.
- ▶ Approximately 24,900 visitors (34 percent of all **e**lectronica visitors), were interested in **e**lectronica embedded in 2014.
- ▶ The Embedded sector met expectations and received outstanding marks: 96 percent of visitors gave the sector a rating of good to excellent.
- ▶ New in 2016: In the Embedded Platforms Village, exhibitors will demonstrate their concentrated embedded know-how at a joint exhibition stand in Hall A6.

# Conference Program

NOVEMBER 9, 2016 – DAY 1

09:30–17:30

MESSE MÜNCHEN, PRESS CENTER EAST

Program last updated 08/16.  
The up-to-date program is available at  
[electronica.de/event-database](http://electronica.de/event-database)

Time	Track No.	IoT and security	Speaker
09:30	Conference opening Track 1		
09:45	1.1	Can emerging megatrends ensure innovative and profitable IoT solutions?	Mike Noonan, Silego Technology
10:35	1.2	IoT-Filling the integration gap	Ian Hall, Renesas
11:15	Coffee break		
11:45	1.3	Navigating the future of connected home devices	Gordon Padkin, Thread Group
12:35	1.4	Driving the future with connected cars	Manfred Schlett, Qualcomm
13:15	Lunch break		
14:00	1.5	A holistic approach for securing embedded devices	Andre Schmitz, Green Hills
14:50	1.6	The layers of security for IoT applications	Lars Lydersen, Silicon Labs
15:30	Coffee break		
16:00	1.7	Implementing device level security in ARM-based products	Yossi Har-Nov, NovTech
16:50	Panel discussion: IoT and security		

Time	Track No.	Microcontrollers and peripherals	Speaker
09:30	Conference opening Track 2		
09:45	2.1	Arduino look and feel for multicore	Marcus Gößler, MicroConsult
10:35	2.2	Hit your application sweet spot with the right Cortex-M7 MCU	Jacko Wilbrink, Atmel
11:15	Coffee break		
11:45	2.3	Core independent peripherals super-charge 8-bit microcontrollers	Keith Curtis, Microchip
12:35	2.4	Efficient embedded programming of heterogeneous multicore platforms	Dr. Timo Stripf, Emmtrix
13:15	Lunch break		
14:00	2.5	Create an embedded software application in 15 minutes	Kimberly Dinsmore, Renesas
14:50	2.6	What functional safety module designers need from IC developers	Tom Meany, Analog Devices
15:30	Coffee break		
16:00	2.7	NAND flash in embedded platforms	Eugen Pfumfel, Toshiba
16:50	2.8	Optimizing SSDs for enhanced performance and beyond	Jeffray Hsieh, ATP

# Conference Program

NOVEMBER 10, 2016 – DAY 2

09:30–17:30

MESSE MÜNCHEN, PRESS CENTER EAST

Program last updated 08/16.  
The up-to-date program is available at  
[electronica.de/event-database](http://electronica.de/event-database)

Time	Track No.	Power and sensors (incl. wireless charging)	Speaker
09:30	Conference opening Track 3		
09:45	3.1	Take the guesswork out of processor power	Bob Martin, Atmel Corporation
10:35	3.2	Software power management techniques for IoT sensor applications	Nick Lethaby, Texas Instruments
11:15	Coffee break		
11:45	3.3	Inductive energy and data transmission in novel industrial applications	Achim Endruschat, Fraunhofer IISB
12:35	3.4	Wireless charging—Cutting the last cord	John Leonard, Nordic Semiconductor
13:15	Lunch break		
14:00	3.5	Sensor innovations for IoT markets	Jeane Forget-Funk, Bosch Sensortec
14:50	3.6	Intelligent IO-Link sensors are the glue to implement Internet of Things (IoT) for next-generation factories	Suhel Dhanani, Maxim Integrated
15:30	Coffee break		
16:00	3.7	ADI MEMS switch technology, a switching solution evolution to service RF instrumentation and test system needs	Padraig McDaid and Eric Carty, Analog Devices
16:50	3.8	Creating a capacitive sense interface without firmware development	Parker Dorris, Silicon Labs

Time	Track No.	Embedded communication	Speaker
09:30	Conference opening Track 4		
09:45	4.1	Combining the Power of NFC and BLE	Laurent Dardé, NXP
10:35	4.2	Identification and traceability matters in electronics	Gernot Seeger, Beta Layout
11:15	Coffee break		
11:45	4.3	Localization of mobile objects using spectral ‘fingerprints’, based on an integrated 40- $\mu$ W UHF broadband wireless receiver	Markus Eppel, Fraunhofer Inst. für Integrierte Schaltungen
12:35	4.4	RTOS-based software development approach for IoT low-power wireless applications	Leo Hendrawan, Texas Instruments
13:15	Lunch break		
14:00	4.5	Sub-1 GHz and Bluetooth® low-energy wireless communication for local and Cloud-based control	Ram Machness, Texas Instruments
14:50	4.6	Introducing NFC commissioning	Pierre Goarin, NXP
15:30	Coffee break		
16:00	4.7	Bringing popular IoT framework to industrial needs	Roman Alyautdin and Hubert Hafner, RTSOFT
16:50	4.8	Surviving the protocol jungle	Dirk Fischer, Hilscher